

# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

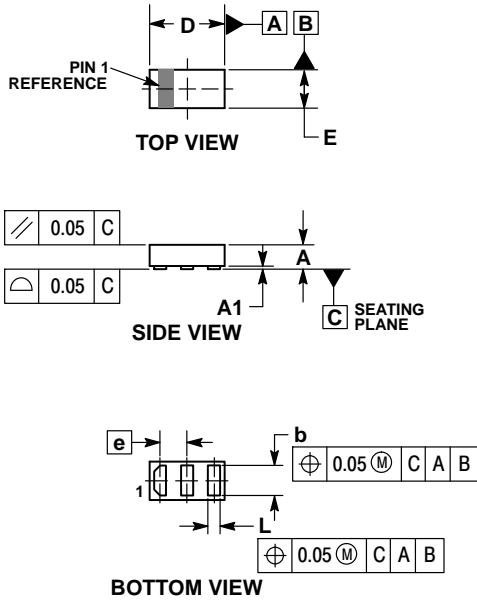
ON Semiconductor®



SCALE 8:1

**X4DFN3 0.62x0.32, 0.225P**  
**CASE 718AB**  
**ISSUE A**

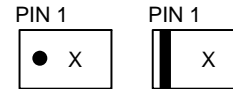
DATE 13 MAR 2018



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETERS.

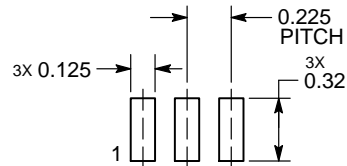
MILLIMETERS			
DIM	MIN	NOM	MAX
A	0.175	0.20	0.225
A1	0.000	0.015	0.030
b	0.23	0.25	0.27
D	0.595	0.620	0.645
E	0.295	0.320	0.345
e	0.225 BSC		
L	0.08	0.10	0.12

### GENERIC MARKING DIAGRAMS\*



X = Specific Device Code

### RECOMMENDED MOUNTING FOOTPRINT\*



DIMENSIONS: MILLIMETERS

See Application Note AND8398/D for more mounting details  
 \*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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<b>DESCRIPTION:</b>	<b>X4DFN3 0.62x0.32, 0.225P</b>	<b>PAGE 1 OF 1</b>

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